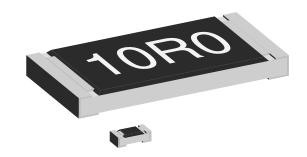
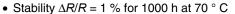


Lead (Pb)-free Thick Film, Rectangular Chip Resistors



FEATURES





- Pure tin solder contacts on Ni barrier layer RoHS provides compatibility with lead (Pb)-free and lead COMPLIANT containing soldering processes
 - HALOGEN FREE
- Metal glaze on high quality ceramic
- Compliant to RoHS directive 2002/95/EC
- Halogen-free according to IEC 61249-2-21 definition
- AEC-Q200 qualified, rev. C compliant

STANDARD	ELEC	CTRICA	L SPECIFICATION	IS							
MODEL	MODEL SINCH		POWER RATING P _{70 °C} W			TOLERANCE %	$\begin{array}{c} \textbf{RESISTANCE} \\ \textbf{RANGE} \\ \Omega \end{array}$	E-SERIES			
				30	± 100	± 1	47R to 1M0	24 + 96			
CRCW0201	0201	RR0603	0.05		± 200	± 1 ± 5	10R to 1M0	24 + 96 24			
			Zero-Ohm-Resistor: R _m	$ax = 50 \text{ m}\Omega, I$	max. at 70 °C = 1.0	A					
D10/CRCW0402	0402	RR1005	0.063	50	± 100 ± 200	± 1 ± 5	1R0 to 10M	24 + 96 24			
			Zero-Ohm-Resistor: R _m	$_{\rm ax.}$ = 20 m Ω , $I_{\rm i}$	_{max.} at 70 °C = 1.5 A	1					
D11/CRCW0603	0603	0603	RR1608	0.10	75	± 100 ± 200	± 1 ± 5	1R0 to 10M	24 + 96 24		
			Zero-Ohm-Resistor: $R_{\text{max.}} = 20 \text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 2.0 A								
D12/CRCW0805	0805	RR2012	0.125	150	± 100 ± 200	± 1 ± 5	1R0 to 10M	24 + 96 24			
			Zero-Ohm-Resistor: R _m	$_{\rm ax.}$ = 20 m Ω , $I_{\rm i}$	$_{max.}$ at 70 °C = 2.5 A	4					
D25/CRCW1206	1206	RR3216	0.25	200	± 100 ± 200	± 1 ± 5	1R0 to 10M	24 + 96 24			
			Zero-Ohm-Resistor: $R_{\text{max.}} = 20 \text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 3.5 A								
CRCW1210	1210	RR3225	0.5	200	± 100 ± 200	± 1 ± 5	1R0 to 10M	24 + 96 24			
			Zero-Ohm-Resistor: $R_{\text{max.}} = 20 \text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 5.0 A								
CRCW1218	1218	RR3246	1.0	200	± 100 ± 200	± 1 ± 5	1R0 to 2M2	24 + 96 24			
			Zero-Ohm-Resistor: $R_{\text{max.}} = 20 \text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 7.0 A								
CRCW2010	2010	RR5025	0.75	400	± 100 ± 200	± 1 ± 5	1R0 to 10M	24 + 96 24			
			Zero-Ohm-Resistor: R _m	$ax. = 20 \text{ m}\Omega, I_1$	$_{\text{max.}}$ at 70 °C = 6.0 A	1					
CRCW2512	2512	2 RR6332	1.0	500	± 100 ± 200	± 1 ± 5	1R0 to 10M	24 + 96 24			
			Zero-Ohm-Resistor: R _m	$_{\rm ax.}$ = 20 m Ω , $I_{\rm i}$	$_{\text{max.}}$ at 70 °C = $\overline{7.0 \text{ A}}$	\					

Notes

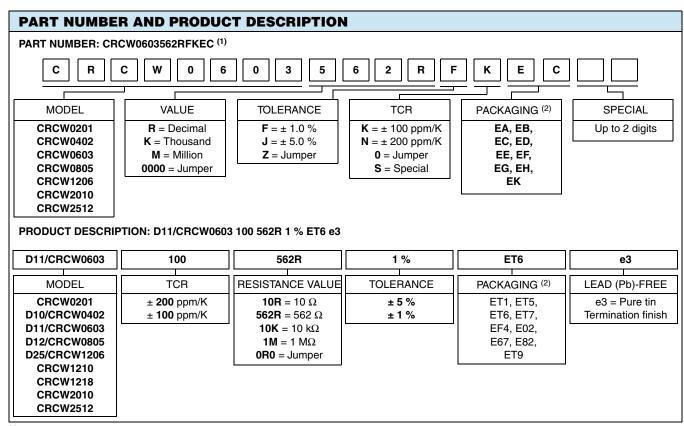
- These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.
- Marking: See data sheet "Surface Mount Resistor Marking" (document number 20020)
- · Power rating depends on the max. temperature at the solder point, the component placement density and the substrate material



TECHNICAL SPECIFICATIONS										
PARAMETER	UNIT	CRCW0201	D10/ CRCW0402	D11/ CRCW0603	D12/ CRCW0805	D25/ CRCW1206	CRCW1210	CRCW1218	CRCW2010	CRCW2512
Rated Dissipation $P_{70}^{(1)}$	W	0.05	0.063	0.1	0.125	0.25	0.5	1.0	0.75	1.0
Limiting Element Voltage $U_{\rm max.}$ AC/DC	٧	30	50	75	150	200	200	200	400	500
Insulation Voltage U _{ins} (1 min)	٧	50	> 75	> 100	> 200	> 300	> 300	> 300	> 300	> 300
Insulation Resistance	Ω					> 109				
Category Temperature Range	°C	- 55 to + 155								
Failure Rate	h ⁻¹	1 x 10 ⁻⁹	1 x 10 ⁻⁹ 0.3 x 10 ⁻⁹							
Weight	mg	0.17	0.65	2	5.5	10	16	29.5	25.5	40.5

Note

⁽¹⁾ The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature of 155 °C is not exceeded.



Notes

⁽¹⁾ Preferred way for ordering products is by use of the PART NUMBER

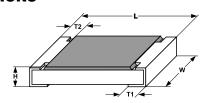
⁽²⁾ Please refer to table PACKAGING, see next page

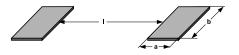
Lead (Pb)-free Thick Film, Rectangular Chip Resistors



PACKAGING										
	REEL									
MODEL	TAPE	DIAMETER		PIECES/	PACKAGING CODE					
WODEL	WIDTH		PITCH	TCH REEL -	PART NUMBER		PRODUCT DESC.			
	WIDIII				PAPER	BLISTER	PAPER	BLISTER		
CRCW0201	8 mm	180 mm/7"	2 mm	10 000	ED		ET7			
0110110201	0 111111	330 mm/13"	2 mm	50 000	EE		EF4			
		180 mm/7"	2 mm	10 000	ED		ET7			
D10/CRCW0402	8 mm	285 mm/11.25"	2 mm	20 000	EC		ET6			
		330 mm/13"	2 mm	50 000	EE		EF4			
		180 mm/7"	4 mm	5000	EA		ET1			
D11/CRCW0603	8 mm	285 mm/11.25"	4 mm	10 000	EB		ET5			
		330 mm/13"	4 mm	20 000	EC		ET6			
	8 mm	180 mm/7"	4 mm	5000	EA		ET1			
D12/CRCW0805		285 mm/11.25"	4 mm	10 000	EB		ET5			
		330 mm/13"	4 mm	20 000	EC		ET6			
		180 mm/7"	4 mm	5000	EA		ET1			
D25/CRCW1206	8 mm	285 mm/11.25"	4 mm	10 000	EB		ET5			
		330 mm/13"	4 mm	20 000	EC		ET6			
		180 mm/7"	4 mm	5000	EA		ET1			
CRCW1210	8 mm	285 mm/11.25"	4 mm	10 000	EB		ET5			
		330 mm/13"	4 mm	20 000	EC		ET6			
CRCW1218	12 mm	180 mm/7"	4 mm	4000		EK		ET9		
CRCW2010	12 mm	180 mm/7"	4 mm	4000		EF		E02		
CRCW2512	10 mm	180 mm/7"	8 mm	2000		EG		E67		
On0W2312	12 mm	100 111111/1	4 mm	4000		EH		E82		

DIMENSIONS





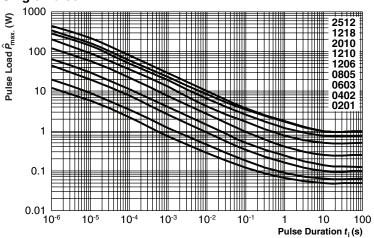
	17F	DIMENSIONS (in millimeters)					SOLDER PAD DIMENSIONS [in millimeters]						
SIZE		DIMENSIONS [in millimeters]					REFLOW SOLDERING			WAVE SOLDERING			
INCH	METRIC	L	w	н	T1	T2	а	b	I	а	b	I	
0201	0525	0.6 ± 0.05	0.3 ± 0.05	0.23 ± 0.05	0.15 ± 0.05	0.15 + 0.05	0.28	0.43	0.23				
0402	1005	1.0 ± 0.05	0.5 ± 0.05	0.35 ± 0.05	0.25 ± 0.05	0.2 ± 0.1	0.4	0.6	0.5				
0603	1608	1.55 + 0.10	0.85 ± 0.1	0.45 ± 0.05	0.3 ± 0.2	0.3 ± 0.2	0.5	0.9	1.0	0.9	0.9	1.0	
0805	2012	2.0 + 0.20 - 0.10	1.25 ± 0.15	0.45 ± 0.05	0.3 + 0.20	0.3 ± 0.2	0.7	1.3	1.2	0.9	1.3	1.3	
1206	3216	3.2 + 0.10	1.6 ± 0.15	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	0.9	1.7	2.0	1.1	1.7	2.3	
1210	3225	3.2 ± 0.2	2.5 ± 0.2	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	0.9	2.5	2.0	1.1	2.5	2.2	
1218	3246	3.2 + 0.10	4.6 ± 0.15	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	1.05	4.9	1.9	1.25	4.8	1.9	
2010	5025	5.0 ± 0.15	2.5 ± 0.15	0.6 ± 0.1	0.6 ± 0.2	0.6 ± 0.2	1.0	2.5	3.9	1.2	2.5	3.9	
2512	6332	6.3 ± 0.2	3.15 ± 0.15	0.6 ± 0.1	0.6 ± 0.2	0.6 ± 0.2	1.0	3.2	5.2	1.2	3.2	5.2	

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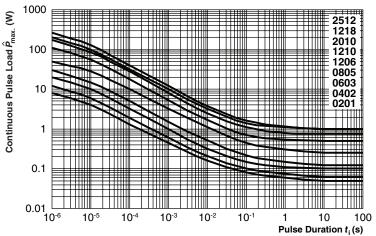
FUNCTIONAL PERFORMANCE

Single Pulse



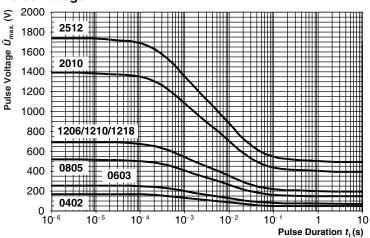
Maximum pulse load, single pulse; applicable if \bar{P} \rightarrow 0 and n < 1000 and $\hat{U} \leq \hat{U}_{max}$; for permissible resistance change equivalent to 8000 h operation

Continuous Pulse



Maximum pulse load, continuous pulses; applicable if $\bar{P} \leq P$ (9_{amb}) and $\hat{U} \leq \hat{U}_{max}$; for permissible resistance change equivalent to 8000 h operation

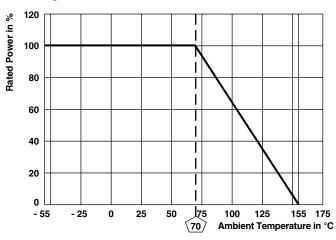
Pulse Voltage



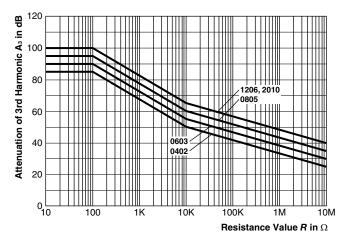
Maximum pulse voltage, single and continuous pulses; applicable if $\hat{P} \leq \hat{P}_{max.}$; for permissible resistance change equivalent to 8000 h operation



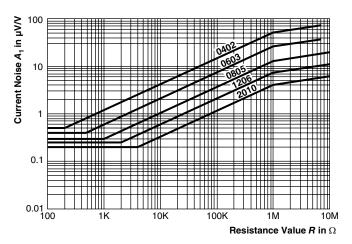
Derating



Non-Linearity



Current Noise





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TEST I	PROCED	URES AND REG	UIREMENTS					
	IEC			PER	REQUIREMENTS MISSIBLE CHANGE (∆ R)		
EN 60115-1	60068-2	TEST	PROCEDURE	SIZE 0402	2 to 2512	SIZE 0201		
CLAUSE	TEST METHOD	1231	PHOCESONE	STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER	REQUIREMENTS PERMISSIBLE CHANGE (ΔR/R)		
			Stability for product types:					
			D/CRCW e3	1 Ω to 10 M Ω	1 Ω to 10 M Ω	10 Ω to 1 M Ω		
4.5	-	Resistance	-	± 1 %	± 5 %	± 1 %; ± 5 %		
4.7	-	Voltage proof	$U = 1.4 \times U_{ins}$; 60 s	No	flashover or breakdow	<i>y</i> n		
4.13	-	Short time overload	$U = 2.5 \times \sqrt{P_{70} \times R}$ $\leq 2 \times U_{\text{max.}};$ Duration acc. to style	$\pm (0.25 \% R + 0.05 \Omega)$	$\pm (0.5 \% R + 0.05 \Omega)$	± (1 % R + 0.05 Ω)		
4 17 0	4.17.2 58 (Td) Solderability		Solder bath method; Sn60Pb40 non activated flux; (235 ± 5) °C (2 ± 0.2) s	Good tinning (≥ 95 % covered) no visible damage				
4.17.2			Solder bath method; Sn96.5Ag3Cu0.5 non-activated flux; (245 ± 5) °C (3 ± 0.3) s	Good tinning (≥ 95 % covered) no visible damage				
4.8.4.2	-	Temperature coefficient	(20/- 55/20) °C and (20/125/20) °C	± 100 ppm/K	± 200 ppm/K	± 100 ppm/K, ± 200 ppm/K		
4.32	21 (Uu ₃)	Shear (adhesion)	45N	No visible damage				
4.33	21 (Uu ₁)	Substrate bending	Depth 2 mm; 3 times	No visible damage, no open circuit in bent position $\pm (0.25 \% R + 0.05 \Omega)$ $\pm (0.5 \% R + 0.05 \Omega)$				
4.19	14 (Na)	Rapid change of temperature	30 min. at - 55 °C; 30 min. at 125 °C 5 cycles 1000 cycles	$\pm (0.25 \% R + 0.05 \Omega)$ $\pm (1 \% R + 0.05 \Omega)$	$\pm (0.5 \% R + 0.05 \Omega)$ $\pm (1 \% R + 0.05 \Omega)$	$\pm (0.5 \% R + 0.05 \Omega)$ $\pm (1 \% R + 0.05 \Omega)$		
4.23	_	Climatic sequence:	-	= (* /8/* * 6:00 12)	= (: / : / : : : : : : : : : : : : : : :	= (
4.23.2	2 (Ba)	Dry heat	125 °C; 16 h					
4.23.3	30 (Db)	Damp heat, cyclic	55 °C; ≥ 90 % RH; 24 h; 1 cycle					
4.23.4	1 (Aa)	Cold	- 55 °C; 2 h	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)	± (2 % R + 0.1 Ω)		
4.23.5	13 (M)	Low air pressure	1 kPa; (25 ± 10) °C; 1 h					
4.23.6	30 (Db)	Damp heat, cyclic	55 °C; ≥ 90 % RH; 24 h; 5 cycles					
4.23.7	-	DC load	$U = \sqrt{P_{70} \times R}$					
4.25.1		Endurance	$U = \sqrt{P_{70} \times R} \le U_{\text{max.}};$ 1.5 h on; 0.5 h off;					
4.20. I	-	at 70 °C	70 °C; 1000 h	$\pm (0.5 \% R + 0.05 \Omega)$	± (2 % R + 0.1 Ω)	± (2 % R + 0.1 Ω)		
			70 °C; 8000 h	± (1 % R + 0.05 Ω)	± (4 % R + 0.1 Ω)	± (4 % R + 0.1 Ω)		
4.18.2	58 (Td)	Resistance to soldering heat	Solder bath method (260 ± 5) °C; (10 ± 1) s	$\pm (0.25 \% R + 0.05 \Omega)$	$\pm (0.5 \% R + 0.05 \Omega)$	± (1 % R + 0.05 Ω)		

Lead (Pb)-free Thick Film, Rectangular Chip Resistors



TEST PROCEDURES AND REQUIREMENTS									
	IEC			PER	REQUIREMENTS MISSIBLE CHANGE ((∆ <i>R</i>)			
EN 60115-1	60068-2	TEST	PROCEDURE	SIZE 0402	SIZE 0201				
CLAUSE METHO		1231	PHOCEDONE	STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER	REQUIREMENTS PERMISSIBLE CHANGE (\(\Delta R/R \))			
			Stability for product types:						
			D/CRCW e3	1 Ω to 10 MΩ	1 Ω to 10 M Ω	10 Ω to 1 M Ω			
4.35	-	Flamability, needle flame test	IEC 60695-11-5; 10 s		No burning after 30 s				
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; (93 ± 3) % RH; 56 days	± (1 % R + 0.05 Ω)		± (2 % R + 0.1 Ω)			
4.25.3	-	Endurance at upper category temperature	155 °C, 1000 h	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)	± (2 % R + 0.1 Ω)			
4.40	-	Electrostatic discharge (Human Body Model)	IEC 61340-3-1* 3 pos. + 3 neg. discharges; ESD voltage acc. to size		± (1 % R + 0.05 Ω)				
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol; 50 °C; method 2	No visible damage					
4.30	45 (XA)	Solvent resistance of marking	Isopropyl alcohol; 50 °C; method 1, toothbrush	Marking legible, no visible damage					
4.22	6 (Fc)	Vibration, endurance by sweeping	f = 10 Hz to 2000 Hz; $x, y, z \le 1.5 \text{ mm};$ $A \le 200 \text{ m/s}^2;$ 10 sweeps per axis	$\pm (0.25 \% R + 0.05 \Omega)$	$\pm (0.5 \% R + 0.05 \Omega)$	± (0.5 % R + 0.05 Ω)			
4.37	-	Periodic electric overload	$U = \sqrt{15 \times P_{70} \times R}$ $\leq 2 \times U_{\text{max.}};$ 0.1 s on; 2.5 s off; 1000 cycles		± (1 % R + 0.05 Ω)				
4.27	-	Single pulse high voltage overload, 10 µs/700 µs	$\hat{U} = 10 \text{ x } \sqrt{P_{70} \text{ x } R}$ $\leq 2 \text{ x } U_{\text{max.}};$ 10 pulses	± (1 % R + 0.05 Ω)					

All tests are carried out in accordance with the following specifications:

- EN 60115-1, generic specification
- EN 140400, sectional specification
- EN 140401-802, detail specification
- IEC 60068-2 environmental test procedures

Packaging of components is done in paper or blister tapes according to IEC 60286-3

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